

Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) An electronic device comprising:
 - a substrate on which an interconnect pattern is formed;
 - a chip component that has a base material, the chip component having a first surface on which a pad is formed and a second surface opposite to the first surface, the chip component being mounted in such a manner that the second surface faces the substrate;
 - a passivation film that is formed on the first surface of the chip component, the passivation film formed to avoid at least a part of the pad,
 - a metal layer that is formed of a plurality of layers including a diffusion prevention layer in contact with the pad and an uppermost layer being less oxidizable than the pad, the diffusion prevention layer preventing any diffusion of material formed thereabove into the base material of the chip component;
 - an insulating section that ~~has a first portion disposed on the passivation film and a second portion disposed is formed~~ adjacent to the chip component, the insulating section being formed to come to an end at a position a distance away from the metal layer, the insulating section having a convex surface that draws a curve on a view from which a cross section perpendicular to the first surface of the chip component is taken, the convex surface ascending from the first surface to have a top surface and descending from the top surface in an outward ~~direction, the first portion having a lower surface than the top surface; and~~ direction;
 - a connecting layer that is disposed between the second surface of the chip component and the substrate, the connecting layer being formed in such a manner that the connecting layer and the insulating section is formed integrally; and

an interconnect that is formed to extend from above the uppermost layer of the metal layer to above the interconnect pattern, the interconnect having a first section disposed on the passivation film and a second section disposed over the insulating section, the interconnect covering all the lateral surfaces of the metal layer.

2. (Original) The electronic device as defined by claim 1,
wherein the insulating section is formed of resin.

3-4. (Canceled)

5. (Currently Amended) A method of manufacturing an electronic device, the method comprising:

preparing a chip component and a substrate, the chip component having a base material, the chip component having a first surface on which a pad is formed and a passivation film is formed to avoid at least a part of the pad, the chip component having a second surface being opposite to the first surface, the substrate having an interconnect pattern;
providing an insulating adhesive on the substrate;

mounting the chip component on the ~~substrate~~insulating adhesive in such a manner that the second surface faces the ~~substrate~~insulating adhesive with applying a compressive force between the substrate and the chip component so that the insulating adhesive has a first part and a second part, the first part being interposed between the chip component and the substrate, the second part being disposed adjacent to the chip component, the second part having a convex surface that draws a curve on a view from which a cross section perpendicular to the first surface of the chip component is taken, the convex surface ascending from the first surface to have a top surface and descending from the top surface in an outward direction;

forming a metal layer that includes a plurality of layers including a diffusion prevention layer in contact with the pad and an uppermost layer being less oxidizable than the

pad, the diffusion prevention layer preventing any diffusion of material formed thereabove into the base material of the chip ~~component~~; component; and

~~forming an insulating section to have a convex surface that draws a curve on a view from which a cross section perpendicular to the first surface of the chip component is taken, the convex surface ascending from the first surface to have a top surface and descending from the top surface in an outward direction, the insulating section having a first portion disposed on the passivation film and a second portion disposed adjacent to the chip component, the first portion having a lower surface than the top surface, the insulating section formed to come to an end at a position a distance away from the metal layer; and~~

forming an interconnect in such a manner as to extend from above the uppermost layer of the metal layer to above the interconnect pattern, as to have a first section disposed on the passivation film and a second section disposed over the insulating section, and as to cover all the lateral surfaces of the metal layer.

6. (Original) The method of manufacturing an electronic device as defined by claim 5,

wherein the interconnect is formed of a dispersant including electrically conductive particles.

7. (Original) The method of manufacturing an electronic device as defined by claim 6,

wherein the step of forming the interconnect includes ejecting the dispersant including the electrically conductive particles over the metal layer, the insulating section and the interconnect pattern.

8. (Original) The method of manufacturing an electronic device as defined by claim 5,

wherein the insulating section is formed of a resin.

9. (Original) The method of manufacturing an electronic device as defined by claim 6,

wherein the insulating section is formed of a resin.

10. (Original) The method of manufacturing an electronic device as defined by claim 7,

wherein the insulating section is formed of a resin.

11-12. (Canceled)

17. (Original) A circuit board on which the electronic device defined by claim 1 is mounted.

18. (Original) An electronic instrument having the electronic device defined by claim 1.

19. (Canceled)

20. (Currently Amended) An electronic device comprising:

- a substrate on which an interconnect patten is formed;
- a chip component that has a base material, the chip component having a first surface on which a pad is formed and a second surface opposite to the first surface, the chip component being mounted in such a manner that the second surface faces the substrate;
- a passivation film that is formed on the first surface of the chip component, the passivation film formed to avoid at least a part of the pad;
- a metal layer that is formed of a plurality of layers including a diffusion prevention layer in contact with the pad and an uppermost layer being less oxidizable than the pad, the diffusion prevention layer preventing any diffusion of material formed thereabove into the base material of the chip component;
- an insulating section that ~~has a first portion disposed on the passivation film and a second portion disposed~~is disposed adjacent to the chip component, the insulating

section having a convex surface that draws a curve on a view from which a cross section perpendicular to the first surface of the chip component is taken, the convex surface ascending from the first surface to have a top surface and descending from the top surface in an outward direction, the first portion having a lower surface than the top surface, the insulating section having an edge disposed between the pad and a part of a periphery of the chip component on which the insulating section is disposed, the edge being closest of the insulating section to the pad; and direction;

a connecting layer that is disposed between the second surface of the chip component and the substrate, the connecting layer being formed in such a manner that the connecting layer and the insulating section is formed integrally; and

an interconnect that is formed to extend from above the uppermost layer of the metal layer to above the interconnect pattern, the interconnect having a first section disposed on the passivation film and a second section disposed over the insulating section, the interconnect covering all the lateral surfaces of the metal layer.

21. (New) The electronic device defined by claim 1,
wherein the insulating section has a first portion disposed on the passivation film and a second portion disposed adjacent to the chip component.

22. (New) The electronic device as defined by claim 21, a part of the passivation film on which the first section of the interconnect is disposed being between the pad and the insulating section.

23. (New) The method or manufacturing an electronic device defined by claim 5, the mounting of the chip component is conducted in such a manner that the second part has a first portion disposed on the passivation film and a second portion disposed adjacent to the chip component, the first portion having a lower surface than the top surface, the second part being formed to come to an end at a position a distance away from the metal layer.

24. (New) The electronic device defined by claim 20,
wherein the insulating section has a first portion disposed on the passivation film and a second portion disposed adjacent to the chip component.
25. (New) The electronic device defined by claim 20,
wherein the insulating section has an edge disposed between the pad and a part of the periphery of the chip component on which the insulating section is disposed, the edge being closest of the insulating section to the pad.
26. (New) The electronic device as defined by claim 1,
wherein the insulating section is formed of the same material as the connecting layer.
27. (New) The electronic device as defined by claim 20,
wherein the insulating section is formed of the same material as the connecting layer.